### Silicon N-Channel MOS FET

## **HITACHI**

#### **Application**

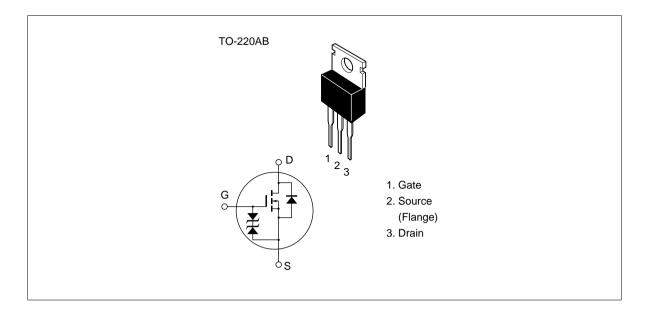
High frequency and low frequency power amplifier, high speed switching.

Complementary pair with 2SJ76, J77, J78, J79

#### **Features**

- Suitable for direct mounting
- High forward transfer admittance
- Excellent frequency response
- Enhancement-mode

#### Outline





#### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

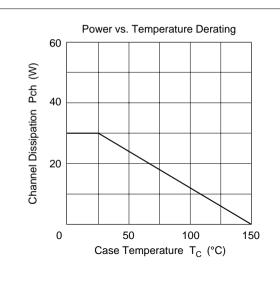
Item		Symbol	Ratings	Unit
Drain to source voltage	Orain to source voltage 2SK213		140	V
	2SK214		160	
	2SK215		180	<del></del>
	2SK216		200	
Gate to source voltage		$V_{GSS}$	±15	V
Drain current		I <sub>D</sub>	500	mA
Body to drain diode reverse drain current		I <sub>DR</sub>	500	mA
Channel dissipation		Pch	1.75	W
		Pch*1	30	W
Channel temperature		Tch	150	°C
Storage temperature		Tstg	-45 to +150	°C

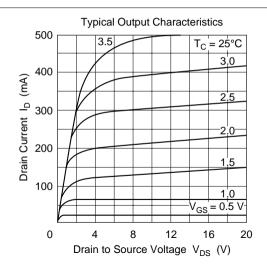
Note: 1. Value at  $T_c = 25^{\circ}C$ 

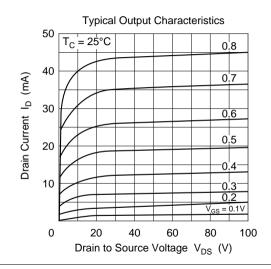
### **Electrical Characteristics** (Ta = 25°C)

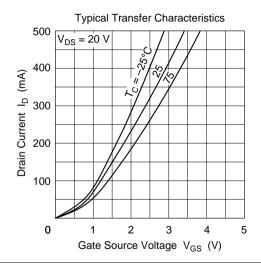
Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SK213	$V_{(BR)DSX}$	140	_	_	V	$I_D = 1 \text{ mA}, V_{GS} = -2 \text{ V}$
breakdown voltage	2SK214	_	160	_	_	V	
	2SK215		180	_	_	V	
	2SK216		200	_	_	V	
Gate to source breakdown voltag		$V_{(BR)GSS}$	±15	_	_	V	$I_{G} = \pm 10 \ \mu A, \ V_{DS} = 0$
Gate to source voltage		V <sub>GS(on)</sub>	0.2	_	1.5	V	$I_D = 10 \text{ mA}, V_{DS} = 10 \text{ V}^{*1}$
Drain to source saturation voltage		$V_{DS(sat)}$	_	_	2.0	V	$I_D = 10 \text{ mA}, V_{GD} = 0 *1$
Forward transfer admittance		y <sub>fs</sub>	20	40	_	mS	$I_D = 10 \text{ mA}, V_{DS} = 20 \text{ V}^{*1}$
Input capacitance		Ciss	_	90	_	pF	$I_D = 10 \text{ mA}, V_{DS} = 10 \text{ V},$
Reverse transfer capacitance		Crss	_	2.2	_	pF	f = 1 MHz

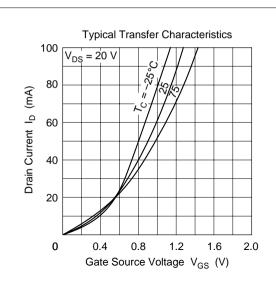
Note: 1. Pulse test

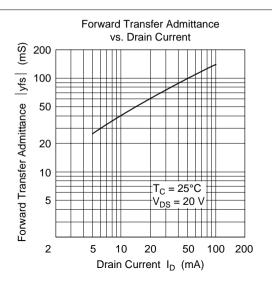


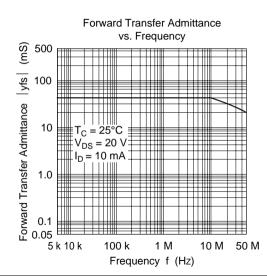




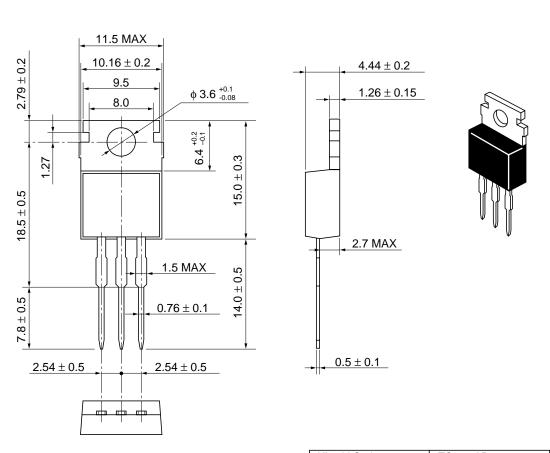








Unit: mm



Hitachi Code	TO-220AB
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.8 g

#### **Cautions**

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